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contact pads 38D. Alternately other types of terminal contacts such as pins, flat pads, or shaped wires can be employed. The terminal contacts 84 are adapted to electrically engage mating electrical connectors (not shown) on a test apparatus 96 (Figure 9A), such as a burn-in board. The test apparatus 96 includes, or is in electrical communication with test circuitry 98, adapted to apply test signals to the integrated circuits contained on the components 18A, and to analyze the resultant signals. The test carrier 80, test apparatus 96, and test circuitry 98 form a test system 100 (Figure 9A).--

On page 13, line 27 to page 14, line 2, please substitute the following clean replacement paragraph:

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--As shown in Figure 3D, the leads 22B also include an outer layer 46B, which comprises a material selected to provide a non-bonding surface for the bumped contacts 16. For example, for bumped contacts 16 formed of solder, the outer layer 46B can comprise a metal that is not solder wettable. Suitable metals include Ti, $TiSi_2$ and Al. Rather than metal, the outer layer 46B can comprise a conductive polymer selected to provide a non-bonding surface. Suitable conductive polymers include carbon films and metal filled silicone.--

In the claims

Please amend claims 1, 2, 5-12, 17, 18, 25-27, 31 and 32. Following is a clean version of the amended claims, which represents all of the pending claims. In addition, a marked version showing the changes to the amended claims follows the Remarks section of this Amendment.